**EAST Search History**

**EAST Search History (Prior Art)**

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------|-----|------------------|---------|------------|
| L2 | 5166 | WAFER SAME SOLAR SAME CELL$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 14:40 |
| L3 | 113 | l2 SAME IMAGE$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 14:41 |
| L4 | 14 | l3 SAME (MATCH$3 OR COMPAR$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 14:42 |
| L5 | 2 | L4 and (@ad<"20040202" or @rlad<"20040202" or @prad<"20040202" or @ptad<"20040202") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 14:42 |
| L6 | 2 | L4 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 14:42 |
| L7 | 1734 | 136/249,262,243,252,246.CCLS. | USPAT | OR | ON | 2010/10/21 15:41 |
| L8 | 1674 | 382/145,141.CCLS. | USPAT | OR | ON | 2010/10/21 15:41 |
| L9 | 2037 | 356/72,237.1,30.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |
| L10 | 8829 | 438/381,396,933,48,57,73,74,93,94,970,584,585,586.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |

| L11 | 6253 | 365/201,63.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |
|-----|------|------------------|-------|----|----|-----------------|
| L12 | 5009 | 429/185,162,210,90,217,218.1,337,59,157,223.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |
| L13 | 9076 | 257/461,414,428,431,461,E27.089,E27.001,E27.009,E27.01,E27.07,E27.081, E27.084,E27.085,E27.086,E27.089,E27.081,E27.098,E27.101,257,E27.122, E27.127,E27.128,E31.001,E31.11,E31.113,E31.114,E31.115.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |
| L14 | 1905 | 204/252,193,194,242,252.CCLS. | USPAT | OR | ON | 2010/10/21 15:42 |
| L15 | 243 | L7 and WAFER SAME SOLAR SAME CELL$1 | USPAT | OR | ON | 2010/10/21 15:43 |
| L17 | 22 | L15 and IMAGE$1 | USPAT | OR | ON | 2010/10/21 15:45 |
| L18 | 21 | L17 and(MATCH$3 OR COMPAR$4) | USPAT | OR | ON | 2010/10/21 15:45 |
| L19 | 18 | L18 and @ad< "20040202" | USPAT | OR | ON | 2010/10/21 15:46 |
| L20 | 6 | L19 and(imaging or ccd or camera or CMOS or IR) | USPAT | OR | ON | 2010/10/21 15:51 |
| L21 | 0 | L20 and(producing or obtaining or generat$3)and wafer adj image same cell adj image | USPAT | OR | ON | 2010/10/21 15:53 |
| L22 | 0 | L8 and WAFER SAME SOLAR SAME CELL$1 | USPAT | OR | ON | 2010/10/21 15:54 |
| L23 | 3 | L8 and WAFER and SOLAR and CELL$1 | USPAT | OR | ON | 2010/10/21 15:54 |
| L24 | 5 | L9 and WAFER and SOLAR and CELL$1 | USPAT | OR | ON | 2010/10/21 15:56 |
| L25 | 4 | L24 and(MATCH$3 OR COMPAR$4) | USPAT | OR | ON | 2010/10/21 15:57 |
| L26 | 0 | L25 and(producing or obtaining or generat$3)and wafer adj image same cell adj image | USPAT | OR | ON | 2010/10/21 15:57 |
| L27 | 2 | L25 and(imaging or ccd or camera or CMOS or IR) | USPAT | OR | ON | 2010/10/21 15:58 |
| L28 | 297 | L10 and WAFER and SOLAR and CELL$1 | USPAT | OR | ON | 2010/10/21 16:03 |
| L29 | 218 | L28 and(MATCH$3 OR COMPAR$4) | USPAT | OR | ON | 2010/10/21 16:03 |

| L30 | 0 | L29 and(producing or obtaining or generat$3)and wafer adj image same cell adj image | USPAT | OR | ON | 2010/10/21 16:03 |
|---|---|---|---|---|---|---|
| L31 | 51 | L29 and(imaging or ccd or camera or CMOS or IR) | USPAT | OR | ON | 2010/10/21 16:04 |
| L32 | 196 | L29 and(compar$3 or match$3)and(solar adj cell or cell crystallographic adj structure or wafer or ingot or cells or cell) | USPAT | OR | ON | 2010/10/21 16:05 |
| L33 | 27 | L32 and(compar$3 or match$3)same wafer same(solar adj cell or cell) | USPAT | OR | ON | 2010/10/21 16:06 |
| L34 | 23 | L33 and(@ad< "20040202" or @rlad< "20040202" or @prad< "20040202" or @ptad< "20040202") | USPAT | OR | ON | 2010/10/21 16:06 |
| L35 | 20 | L33 and @ad< "20040202" | USPAT | OR | ON | 2010/10/21 16:07 |
| L36 | 1 | L35 and(imaging or ccd or camera or CMOS or IR) | USPAT | OR | ON | 2010/10/21 16:08 |
| S1 | 2124 | sheela chawan.Xa. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:40 |
| S2 | 2338 | sheela chawan.Xp. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:46 |
| S3 | 2 | S1 and wafer adj polishing | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:46 |
| S4 | 2 | S2 and wafer adj polishing | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:47 |
| S5 | 22 | S1 and wafer adj inspection | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:48 |

| S6 | 22 | S2 and wafer adj inspection | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 15:48 |
|---|---|---|---|---|---|---|
| S7 | 156 | wafer adj pad and inspection | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/09 16:05 |
| S8 | 156 | wafer adj pad and inspection | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:04 |
| S9 | 27 | S8 and notch | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:04 |
| S10 | 337122 | crystallographic asj structure and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:09 |
| S11 | 966 | crystallographic adj structure and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:09 |
| S12 | 191 | crystallographic adj structure same wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:09 |
| S13 | 150 | S12 and (@ad<"20040202" or @rlad<"20040202" or @prad<"20040202" or @ptad<"20040202") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:21 |

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|---|---|---|---|---|---|---|
| S14 | 117 | S12 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:21 |
| S15 | 16 | S14 and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:22 |
| S16 | 16 | S15 and (compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:23 |
| S17 | 41 | crystallographic adj structure and wafer and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:39 |
| S18 | 5 | S17 and(compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:40 |
| S19 | 4 | S18 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:40 |
| S20 | 110 | (("4352948" or "6161054" or "5203005" or "5287472" or "5292677" or "5485097" or "6243308" or "4435498" or "4471483" or "4493055" or "4519035" or "4543444" or "4898835" or "4999689" or "5019736" or "5024972" or "5252507" or "5265847" or "5315130" or "5362666" or "5393617" or "5478363" or "5491665" or "5536964" or "5552243" or "5619419" or "5624771" or "5656392" or "5657284" or "5698453" or "5698342" or "5716459" or "5808947" or "5821160" or "5851693" or "5926419" or "6040912" or "RE36644" or "6046078" or "6140140" or "6161213" or "6225167" or "6330819" or "4304641" or "4338480" or "4353160" or "4385198" or "4400221" or "4400868" or (").pn.")). PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/03/10 16:43 |

| S21 | 106 | S20 and(@ad<"20040202" or @rlad<"20040202" or @prad<"20040202" or @ptad<"20040202") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:43 |
|-----|-----|---|---|---|---|---|
| S22 | 106 | S20 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:43 |
| S23 | 0 | S22 and crystallographic adj structure and wafer and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:44 |
| S24 | 0 | S22 and crystallographic adj structure and wafer and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 16:46 |
| S25 | 5 | S22 and inspect$3 and(crystallographic adj structure or wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:05 |
| S26 | 4 | S25 and(compar$3 or match$3)and(solar adj cell or cell crystallographic adj structure or wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:06 |
| S27 | 4 | S26 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:07 |
| S28 | 4742 | crystallographic adj structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:10 |

| S29 | 4328355 | (wafer$1 or semiconductor or solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:11 |
|-----|---------|---------|---------|-----|-----|---------|
| S30 | 98638 | S29 and inspect$3 and(cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:20 |
| S31 | 153527 | S29 and inspect$3 and(cells or cell or wafer or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:21 |
| S32 | 4742 | crystallographic adj structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:22 |
| S33 | 632 | S31 and S32 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:27 |
| S34 | 1 | S33 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:28 |
| S35 | 3 | inspect$3 and solar adj cell and matrix and convert$3 and electricity and solar adj cell and treating and silicon adj wafers and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:32 |
| S36 | 2 | S35 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:33 |

| S37 | 1 | S35 and (compar$3 or match$3)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:39 |
|-----|---|----------------------------------------------------------------------|---------------------------------------------|----|----|------------------|
| S38 | 1 | S32 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:40 |
| S39 | 17 | S29 and (compar$3 or match$3)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:40 |
| S40 | 3 | S39 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:41 |
| S41 | 1 | S39 and crystallographic adj structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:51 |
| S42 | 1 | S39 and crystallographic adj structure and wafer adj structure and manufactured adj cell and crystallographic adj image and information and sufficient adj establish and correspondence and cell and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:58 |
| S43 | 1 | S39 and crystallographic adj structure and wafer adj structure and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:59 |
| S44 | 1 | crystallographic adj structure and wafer adj structure and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 17:59 |

| S45 | 2 | S29 and crystallographic adj structure and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:00 |
|-----|---|-----------------------------------------------------------------|----------------------------------------------|----|----|------------------|
| S46 | 0 | S45 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:01 |
| S48 | 607 | S32 and inspect$3 and(cells or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:06 |
| S49 | 1 | S48 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:06 |
| S50 | 587 | S48 and(compar$3 or match$3)and (memory or cell or memory adj cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:07 |
| S51 | 1 | S48 and(compar$3 or match$3)same(memory or cell or memory adj cell) same wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:08 |
| S52 | 1 | S50 and crystallographic adj structure and wafer adj structure and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:09 |
| S53 | 1 | S50 and wafer adj structure and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:09 |

| S54 | 1 | S50 and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:10 |
| S55 | 297 | S50 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:10 |
| S56 | 12 | S55 and(compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:11 |
| S57 | 13 | S55 and inspect$3 and wafer$1 and(cells or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:12 |
| S58 | 0 | S55 and inspect$3 adj wafer$1 same(cells or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:13 |
| S59 | 0 | S55 and inspect$3 adj wafer$1 and(cells or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:13 |
| S60 | 3559 | S28 and(wafer$1 or semiconductor or solar adj cell or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:14 |
| S61 | 2 | S60 and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:14 |

| S62 | 0 | S61 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:14 |
| S63 | 2 | S32 and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:15 |
| S64 | 1818 | S32 and(wafer$1 or semiconductor or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:16 |
| S65 | 237 | S32 and(wafer$1 or semiconductor or memory)and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:16 |
| S66 | 119 | S65 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:16 |
| S67 | 12 | S66 and(compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:19 |
| S68 | 38 | S32 and inspect$3 and(compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:28 |
| S69 | 41 | S32 and inspect$3 and(compar$3 or match$3)and wafer and(solar adj cell or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:29 |

| S70 | 13 | S69 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:29 |
|-----|-----|--------------------------------------------------------|---------------------------------------------|-----|-----|------------------|
| S71 | 85837 | analyz$3 and(crystalline or crystallographic adj structure) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:35 |
| S72 | 18 | S71 and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:36 |
| S73 | 1 | S72 and(wafer$1 or semiconductor or memory)and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:36 |
| S74 | 1 | inspect$3 and photovoltaic adj area and manufactured and crystalline adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:43 |
| S75 | 0 | S74 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:44 |
| S76 | 0 | S72 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:46 |
| S77 | 0 | S71 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:47 |

| S78 | 31037 | S71 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:47 |
|-----|-------|---|---|---|---|---|
| S79 | 8 | S78 and manufactured adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:47 |
| S80 | 2 | S79 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:48 |
| S81 | 2106 | S78 and(wafer$1 or semiconductor$1 or IC or intergrated adj circuit) and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:51 |
| S82 | 45 | S81 and(compar$3 or match$3)same(memory or cell or memory adj cell) same wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:52 |
| S83 | 18 | S82 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 18:52 |
| S84 | 25 | S17 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 19:17 |
| S85 | 5 | S72 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 19:48 |

| S86 | 118795 | (wafer$1 or semiconductor$1 or IC or intergrated adj circuit) and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 19:49 |
| S87 | 9 | S86 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 19:49 |
| S88 | 1 | S87 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 19:49 |
| S89 | 533 | crystallographic adj structure and(wafer or ingot)and section | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:15 |
| S90 | 161 | S89 and analyz$3 and(crystalline or crystallographic adj structure) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:16 |
| S91 | 0 | S89 and analyz$3 and(crystalline or crystallographic adj structure) same ignot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:16 |
| S92 | 0 | S90 and(imaging or ccd or camera or CMOS or IR)and wafer adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:17 |
| S93 | 120 | S90 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:17 |

| S94 | 48 | S93 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:22 |
|---|---|---|---|---|---|---|
| S95 | 0 | S93 and etching and texturisation | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 20:59 |
| S96 | 7 | (wafer$1 or semiconductor$1 or IC or intergrated adj circuit) and etching and texturisation and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:00 |
| S97 | 2 | S96 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:00 |
| S98 | 0 | S97 and(compar$3 or match$3)same(memory or cell or memory adj cell or die)same wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:01 |
| S99 | 0 | S97 and(compar$3 or match$3)and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:01 |
| S100 | 2 | S97 and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:01 |
| S101 | 161 | S89 and S90 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:05 |

| S102 | 0 | S101 and(wafer$1 or semiconductor$1 or IC or intergrated adj circuit)and etching and texturisation and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:06 |
|------|---|------|------|------|------|------|
| S103 | 0 | S101 and etching and texturisation and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:06 |
| S104 | 0 | S101 and etching and texturisation | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:07 |
| S105 | 1 | S89 and etching and texturisation | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:07 |
| S106 | 20 | S89 and solar adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:08 |
| S107 | 8 | S106 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:08 |
| S108 | 2468 | ingot and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:10 |
| S109 | 523 | S108 and wafer$3 and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:11 |

| S110 | 128 | S109 and cell and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:11 |
| S111 | 1 | S110 and wafer adj position$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:12 |
| S112 | 75 | S110 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:13 |
| S113 | 0 | S112 and cell adj inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:13 |
| S114 | 75 | S112 and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:14 |
| S115 | 0 | S114 and(imaging or ccd or camera or CMOS or IR)and wafer adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:14 |
| S116 | 12 | S114 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:14 |
| S117 | 10 | S116 and(compar$3 or match$3)and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:15 |

| S118 | 10 | S117 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/10 21:15 |
| S119 | 93 | measur$3 and polycrystalline adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:04 |
| S120 | 63 | photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:05 |
| S121 | 0 | defect adj characteriz$3 and classificat$3 and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:07 |
| S122 | 54 | defect and classificat$3 and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:08 |
| S123 | 0 | (defects or grain adj boundaries)and processing adj wafer$1 and classificat $3 and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:09 |
| S124 | 75 | (defects or grain adj boundaries)and processing adj wafer$1 and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:10 |
| S125 | 3 | S119 and S120 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:10 |

| S126 | 0 | S124 and S125 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:11 |
| S127 | 0 | S125 and(defects or grain adj boundaries)and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:11 |
| S128 | 0 | S125 and(defects or grain adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:12 |
| S129 | 0 | S125 and defects and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:12 |
| S130 | 10 | S120 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:15 |
| S131 | 3 | S130 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:16 |
| S132 | 0 | S120 and inspect$3 adj defects and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:29 |
| S133 | 0 | S120 and inspect$3 and defects and crystal adj growth and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:29 |

| S134 | 4 | S120 and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:30 |
|------|---|--------------------|------|----|----|------------------|
| S135 | 1 | S134 and(defects or grain adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:30 |
| S136 | 0 | S135 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:30 |
| S137 | 55 | S120 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:35 |
| S138 | 1 | S137 and(imaging or ccd or camera or CMOS or IR)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:35 |
| S139 | 0 | S138 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:36 |
| S140 | 55 | S120 and S137 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:36 |
| S141 | 20 | S140 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:36 |

| S142 | 13 | S141 and(compar$3 or match$3)and(wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:44 |
|------|----|-------------------------------------------------------------------|------|----|----|-------------------|
| S143 | 11 | S141 and(compar$3 or match$3)same(wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:46 |
| S144 | 11 | S143 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:46 |
| S145 | 0 | S141 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:49 |
| S146 | 0 | S141 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:50 |
| S147 | 0 | S137 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:50 |
| S148 | 0 | S120 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:51 |
| S149 | 0 | S120 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:51 |

| S150 | 0 | S119 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:52 |
| S151 | 0 | S124 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:52 |
| S152 | 0 | S120 and(imaging or ccd or camera or CMOS or IR)and(compar$3 or match $3)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:53 |
| S153 | 5 | (imaging or ccd or camera or CMOS or IR)and(compar$3 or match$3)and photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:54 |
| S154 | 2 | S153 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:54 |
| S155 | 2 | S154 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 10:55 |
| S156 | 4 | S120 and(wafer$1 or semiconductor$1 or IC or intergrated adj circuit) and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:04 |
| S157 | 10 | S119 and(wafer$1 or semiconductor$1 or IC or intergrated adj circuit) and inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:04 |

| S158 | 0 | S156 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3)and surface adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:04 |
| S159 | 0 | S156 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:05 |
| S160 | 0 | S157 and(imaging or ccd or camera or CMOS or IR)and wafer adj image and cell adj image and(compar$3 or match$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:05 |
| S161 | 0 | S157 and(imaging or ccd or camera or CMOS or IR)and(compar$3 or match $3)and photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:05 |
| S162 | 0 | S157 and(imaging or ccd or camera or CMOS or IR)and(compar$3 or match $3)and (cell adj solar or cell or memory or wafer$1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:06 |
| S163 | 4 | S157 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:06 |
| S164 | 4 | S163 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:06 |
| S165 | 1 | S164 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:07 |

| S166 | 0 | S119 and produc$4 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:16 |
|---|---|---|---|---|---|---|
| S167 | 0 | S120 and produc$4 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:16 |
| S168 | 0 | S122 and produc$4 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:16 |
| S169 | 0 | S122 and(produc$4 or obtaining)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:16 |
| S170 | 0 | S157 and(produc$4 or obtaining)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:17 |
| S171 | 0 | S153 and(produc$4 or obtaining)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:17 |
| S172 | 0 | S155 and(produc$4 or obtaining)and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:17 |
| S173 | 1 | crystallographic adj structure and(produc$4 or obtaining)and wafer adj image and cell adj image and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:18 |

| S174 | 1 | crystallographic adj structure and(produc$4 or obtaining)and wafer adj image and(cell adj image or cells or cell or wafer or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:20 |
|------|---|---|---|---|---|---|
| S175 | 3130 | crystallographic adj structure and(produc$4 or obtaining)and(cell adj image or cells or cell or wafer or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:20 |
| S176 | 2 | S175 and photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:21 |
| S177 | 2 | S176 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:21 |
| S178 | 0 | S177 and(imaging or ccd or camera or CMOS or IR or image) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:31 |
| S179 | 1586 | S175 and(imaging or ccd or camera or CMOS or IR or image) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:31 |
| S180 | 0 | S179 and photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:32 |
| S181 | 0 | S179 and photovoltaic adj devices and(slicing or dice$3 or diced)and (ingot or wafer$1 or semiconductor$1 or IC or intergrated adj circuit)and inspect $3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:33 |

| S182 | 2 | S175 and photovoltaic adj devices and(slicing or dice$3 or diced)and (ingot or wafer$1 or semiconductor$1 or IC or intergrated adj circuit) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:34 |
|------|---|---|---|---|---|---|
| S183 | 2 | S182 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:34 |
| S184 | 2 | S183 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries or grain adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/11 11:37 |
| S185 | 850 | wafer$1 adj identification | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:14 |
| S186 | 1 | S185 and etching and texturisation | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:14 |
| S187 | 348 | S185 and (etching or texturisation) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:15 |
| S188 | 48 | wafer$1 adj identification same(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:16 |
| S189 | 12 | S188 and (etching or texturisation) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:16 |

| S190 | 0 | S189 and phosphorus adj doping | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:16 |
| S191 | 0 | S189 and phosphorus and doping | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:17 |
| S192 | 8 | S189 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:17 |
| S193 | 0 | S188 and phosphorus adj doping | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:21 |
| S194 | 1323 | phosphorus adj doping | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:21 |
| S195 | 872 | S194 and (etching or texturisation) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:21 |
| S196 | 1 | S195 and wafer$1 adj identification and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:21 |
| S197 | 29 | S195 and identification and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:23 |

| S198 | 16 | S197 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:23 |
| S199 | 0 | S198 and edge adj etching | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:23 |
| S200 | 14 | S198 and edge and etching | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:23 |
| S201 | 0 | S200 and oxide adj removal | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:24 |
| S202 | 10 | S200 and oxide and removal | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:24 |
| S203 | 1323 | phosphorus adj doping | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:25 |
| S204 | 898 | S203 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:25 |
| S205 | 8 | S204 and oxide adj removal | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:26 |

| S206 | 0 | S205 and antireflective adj coating | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:26 |
| S207 | 0 | S205 and screen adj print | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:27 |
| S208 | 1 | S203 and inspect$3 adj wafer$1 and(cells or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:28 |
| S209 | 1 | S203 and wafer$1 adj identification and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:29 |
| S210 | 566 | wafer$1 and screen adj print | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:29 |
| S211 | 15 | S210 and antireflective adj coating | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:30 |
| S212 | 2 | S211 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:30 |
| S213 | 0 | S198 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:34 |

| S214 | 1 | S203 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:34 |
| S215 | 1 | determining adj quality and wafer adj production and cell adj production and process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:36 |
| S216 | 12 | quality and wafer adj production and cell adj production and process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:37 |
| S217 | 1 | S216 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:37 |
| S218 | 2 | S216 and identification and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:37 |
| S219 | 0 | S218 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:38 |
| S220 | 8 | S216 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/12 12:40 |
| S221 | 22 | Ingot adj production and wafer adj production | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 11:52 |

| S222 | 10 | S221 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 11:53 |
| S223 | 0 | Ingot adj production and wafer adj production same(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:07 |
| S224 | 6 | Ingot adj production same(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:07 |
| S225 | 4 | S224 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:07 |
| S226 | 0 | S224 and cell adj inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:12 |
| S227 | 1 | S221 and cell adj inspect$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:12 |
| S228 | 0 | cell adj inspect$3 and wafer adj production same(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:14 |
| S229 | 0 | cell adj inspect$3 and wafer adj production and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:14 |

| S230 | 22 | cell adj inspect$3 and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:14 |
| S231 | 6 | S230 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 12:18 |
| S232 | 0 | cell adj inspect$3 and imageing and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 13:05 |
| S233 | 140 | image$3 and cell adj image and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 13:06 |
| S234 | 0 | S233 and Ingot adj production same(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 13:06 |
| S235 | 0 | S233 and Ingot adj production and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 13:07 |
| S236 | 2 | "6140140".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/16 14:52 |
| S237 | 23 | cell adj inspect$3 and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:19 |

| S238 | 6 | S237 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:19 |
| S239 | 3 | S238 and (breakage or damage) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:21 |
| S240 | 64 | photovoltaic adj devices and(slicing or dice$3 or diced)and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:23 |
| S241 | 55 | S240 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:23 |
| S242 | 20 | S241 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:24 |
| S243 | 3 | S242 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:25 |
| S244 | 2 | S237 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:36 |
| S245 | 1 | S244 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:37 |

| S246 | 4764 | crystallographic adj structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:37 |
| S247 | 110 | S246 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:37 |
| S248 | 65 | S247 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:38 |
| S249 | 2 | "7144457".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:44 |
| S250 | 0 | S249 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:44 |
| S251 | 0 | S249 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:44 |
| S252 | 2 | "6465781".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:45 |
| S253 | 0 | S252 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:45 |

| S254 | 4764 | crystallographic adj structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:46 |
|---|---|---|---|---|---|---|
| S255 | 1 | S254 and wafer adj image and cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:46 |
| S256 | 110 | ("(4352948") or ("6161054") or ("5203005") or ("5287472") or ("5292677") or ("5485097") or ("6243308") or ("4435498") or ("4471483") or ("4493055") or ("4519035") or ("4543444") or ("4898835") or ("4999689") or ("5019736") or ("5024972") or ("5252507") or ("5265847") or ("5315130") or ("5362666") or ("5393617") or ("5478363") or ("5491665") or ("5536964") or ("5552243") or ("5619419") or ("5624771") or ("5656392") or ("5657284") or ("5698453") or ("5698342") or ("5716459") or ("5808947") or ("5821160") or ("5851693") or ("5926419") or ("6040912") or ("RE36644") or ("6046078") or ("6140140") or ("6161213") or ("6225167") or ("6330819") or ("4304641") or ("4338480") or ("4353160") or ("4385198") or ("4400221") or ("4400868") or (").pn.")). PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/03/27 17:47 |
| S257 | 106 | S256 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:47 |
| S258 | 5 | S257 and inspect$3 and(crystallographic adj structure or wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:47 |
| S259 | 4 | S258 and(compar$3 or match$3)and(solar adj cell or cell crystallographic adj structure or wafer or ingot or cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:47 |
| S260 | 5 | S257 and inspect$3 and(crystallographic adj structure or wafer or ingot or cells) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:47 |

| S261 | 0 | S260 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:48 |
|---|---|---|---|---|---|---|
| S262 | 0 | S260 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:48 |
| S263 | 142 | image$3 and cell adj image and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:48 |
| S264 | 6 | S263 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:48 |
| S265 | 2 | S264 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:49 |
| S266 | 110 | S246 and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:50 |
| S267 | 65 | S266 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:50 |
| S268 | 66 | S267 cell adj image and wafer adj image and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:51 |

| S269 | 66 | S267 cell adj image and wafer adj image same(compar$3 or match$3)same breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:51 |
| S270 | 65 | S269 and @ad< "20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:51 |
| S271 | 2 | "5667597".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:55 |
| S272 | 0 | S271 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:55 |
| S273 | 2 | "6316832".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:56 |
| S274 | 2 | S273 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:56 |
| S275 | 4764 | S254 cell adj image and wafer adj image and(compar$3 or match$3)and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:57 |
| S276 | 1 | S254 and cell adj image and wafer adj image and(compar$3 or match$3) and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:58 |

| S277 | 2 | "5716459".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:58 |
| S278 | 0 | S277 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:59 |
| S279 | 2 | "5153444".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:59 |
| S280 | 0 | S279 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 17:59 |
| S281 | 535 | crystallographic adj structure and(wafer or ingot)and section | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:01 |
| S282 | 1 | S281 and cell adj image same wafer adj image same(compar$3 or match$3) same breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:01 |
| S283 | 2 | "7144457".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:02 |
| S284 | 0 | S283 and(breakage or damaged) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:03 |

| S285 | 42 | S254 and inspect$3 and(compar$3 or match$3)and wafer and(solar adj cell or cell or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:08 |
| S286 | 13 | S285 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:08 |
| S287 | 0 | S286 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:08 |
| S288 | 535 | crystallographic adj structure and(wafer or ingot)and section | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:09 |
| S289 | 162 | S288 and analyz$3 and(crystalline or crystallographic adj structure) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:09 |
| S290 | 120 | S289 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:09 |
| S291 | 48 | S290 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:09 |
| S292 | 0 | S291 and(breakage or damaged) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:09 |

| S293 | 2491 | ingot and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S294 | 525 | S293 and wafer$3 and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S295 | 128 | S294 and cell and production adj process | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S296 | 75 | S295 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S297 | 75 | S296 and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S298 | 12 | S297 and(imaging or ccd or camera or CMOS or IR) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S299 | 10 | S298 and(compar$3 or match$3)and(memory or cell or memory adj cell or die)and wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
| S300 | 10 | S299 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |

| S301 | 6 | S300 and(breakage or damaged) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:11 |
|---|---|---|---|---|---|---|
| S302 | 2 | S300 and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:17 |
| S303 | 2 | "6140140".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:31 |
| S304 | 1 | S303 and memory | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 18:32 |
| S305 | 2 | "5757474".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 21:51 |
| S306 | 0 | S305 and(breakage or damage) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/27 21:56 |
| S307 | 2 | "5757474".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/29 10:00 |
| S308 | 2 | "6482661".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/03/29 10:01 |

| S309 | 111 | (("4352948") or ("6161054") or ("5203005") or ("5287472") or ("5292677") or ("5485097") or ("6243308") or ("4435498") or ("4471483") or ("4493055") or ("4519035") or ("4543444") or ("4898835") or ("4999689") or ("5019736") or ("5024972") or ("5252507") or ("5265847") or ("5315130") or ("5362666") or ("5393617") or ("5478363") or ("5491665") or ("5536964") or ("5552243") or ("5619419") or ("5624771") or ("5656392") or ("5657284") or ("5698453") or ("5698342") or ("5716459") or ("5808947") or ("5821160") or ("5851693") or ("5926419") or ("6040912") or ("RE36644") or ("6046078") or ("6140140") or ("6161213") or ("6225167") or ("6330819") or ("4304641") or ("4338480") or ("4353160") or ("4385198") or ("4400221") or ("4400868") or (").pn.")).PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/03/29 10:02 |
|------|-----|----|----|----|----|----|
| S310 | 0 | ("product$3samesolaradjcells").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/10/15 10:16 |
| S311 | 28478 | product$3 same solar adjc ells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:16 |
| S312 | 9636 | product$3 same solar adj cells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:16 |
| S313 | 1 | S312 and establish$3 adj correspondence same wafers same solar adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:18 |
| S314 | 3 | S312 and establish$3 adj correspondence and wafers and solar adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:18 |
| S315 | 106 | crystallographic adj structure and wafer$1 and solar adj cells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:20 |

| S316 | 5 | S315 and matrix same solar adj cells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:21 |
| S317 | 1 | S314 and solar adj cell and produced and treating and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:23 |
| S318 | 507 | solar adj cell and produced and treating and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:23 |
| S319 | 34 | matrix same solar adj cells and produced and treating and silicon adj wafer $1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:24 |
| S320 | 2 | S319 and silicon adj wafer$1 and cutt$3 and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:26 |
| S321 | 0 | S320 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:26 |
| S322 | 5030 | solar adj cells and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:36 |
| S323 | 0 | solar adj cells and silicon adj wafer$1 same solar adj cell adj traceability | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:36 |

| S324 | 1 | solar adj cells and silicon adj wafer$1 and solar adj cell adj traceability | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:36 |
|------|------|------|------|------|------|------|
| S325 | 9636 | product$3 same solar adj cells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:38 |
| S326 | 8 | S325 and crystallographic adj structure and wafer$1 and solar adj cells | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:39 |
| S327 | 18 | solar adj cells and silicon adj wafer$1 and traceability | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:48 |
| S328 | 5 | S327 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:48 |
| S329 | 72405 | (compar$3 or match$3)and wafer$1 and(solar adj cells or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:57 |
| S330 | 2509 | (compar$3 or match$3)same wafer$1 same(solar adj cells cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:57 |
| S331 | 3 | S330 and matrix same solar adj cells and produced and treating and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:58 |

| S332 | 0 | S331 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 10:58 |
|---|---|---|---|---|---|---|
| S333 | 1 | image$3 adj device and crystallographic adj structure and wafer and cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:02 |
| S334 | 429 | crystallographic adj structure and wafer and cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:03 |
| S335 | 5 | S334 and(compar$3 or match$3)same wafer$1 same(solar adj cells or cell or matrix) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:03 |
| S336 | 3 | S335 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:03 |
| S337 | 0 | S336 and(image$3 adj device or camera or ccd) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:23 |
| S338 | 106 | S334 and(image$3 adj device or camera or ccd) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:23 |
| S339 | 32 | S338 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:23 |

| S340 | 0 | S339 and(compar$3 or match$3)same wafer$1 same(solar adj cells or cell or matrix) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:23 |
| S341 | 27 | S339 and(compar$3 or match$3)and wafer$1 and(solar adj cells or cell or matrix) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:24 |
| S342 | 0 | S341 and matrix same solar adj cells and produced and treating and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:24 |
| S343 | 1 | S341 and matrix and solar adj cells and produced and treating and silicon adj wafer$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:24 |
| S344 | 345 | S334 and(defects or variances or voids or defects or stacking adj faults or inclusions or impurities or grain or crystal adj boundaries or breakage) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:36 |
| S345 | 86 | S344 and(image$3 adj device or camera or ccd) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:37 |
| S346 | 78 | S345 and(compar$3 or match$3)and wafer$1 and(solar adj cells or cell or matrix) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:37 |
| S347 | 0 | S346 and defect same breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:38 |

| S348 | 6 | S346 and defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:38 |
|------|---|------|------|------|------|------|
| S349 | 25 | S346 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:39 |
| S350 | 0 | S334 and(compar$3 or match$3)and wafer$1 and(solar adj cells or cell or matrix)and(software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:44 |
| S351 | 0 | (compar$3 or match$3)and wafer$1 and(solar adj cells or cell or matrix)and (software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:44 |
| S352 | 0 | S334 and(software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:46 |
| S353 | 1 | (software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:46 |
| S354 | 3350 | crystallographic adj structure and(produc$4 or obtaining)and(cell adj image or cells or cell or wafer or memory) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:47 |
| S355 | 0 | S354 and(software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:48 |

| S356 | 0 | S354 and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:48 |
|------|---|---|---|---|---|---|
| S357 | 0 | S334 and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:48 |
| S358 | 0 | inspect$3 and(compar$3 or match$3)and wafer$1 and(solar adj cells or cell or matrix)and(software or program)and image adj recognition and detect adj defect and breakage | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:53 |
| S359 | 0 | inspect$3 adj solar adj cell same wafer$1 adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:54 |
| S360 | 5 | inspect$3 and solar adj cell same wafer$1 adj cell | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:54 |
| S361 | 0 | S360 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 11:54 |
| S362 | 2 | "5257544".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 12:02 |
| S363 | 0 | S360 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 12:06 |

| S364 | 2 | "6760472".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 12:21 |
| S365 | 2 | S364 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/15 12:22 |
| S366 | 2 | "20080160648" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 09:22 |
| S367 | 1 | S366 and software | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 09:22 |
| S368 | 1237 | micro adj defects and(semiconductors or wafer$1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:21 |
| S369 | 5 | S368 and Ingot adj production and(slicing or dice$3 or diced) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:22 |
| S370 | 2 | S369 and (@ad<"20040202" or @rlad<"20040202" or @prad<"20040202" or @ptad<"20040202") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:22 |
| S371 | 2 | S369 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:23 |

| S372 | 0 | S371 and inspect$3 and(crystallographic adj structure or wafer or ingot or cells) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:23 |
| S373 | 0 | S371 and(compar$3 or match$3)same wafer same(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:24 |
| S374 | 584 | detect$3 and micro adj defects and(semiconductors or wafer$1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:25 |
| S375 | 162 | S374 and(compar$3 or match$3)and (memory or cell or memory adj cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:25 |
| S376 | 96 | S375 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:26 |
| S377 | 46 | S374 and(compar$3 or match$3)same(memory or cell or memory adj cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:27 |
| S378 | 246 | S374 and(compar$3 or match$3)same(memory or cell or memory adj cell or wafer$1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:28 |
| S379 | 145 | S378 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:28 |

| S380 | 2 | S379 and(compar$3 or match$3)same wafer same(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:28 |
|------|---|---|---|----|----|----|
| S381 | 0 | S379 and(imaging or ccd or camera or CMOS or IR)same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:32 |
| S382 | 0 | S374 and(imaging or ccd or camera or CMOS or IR)same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:32 |
| S383 | 0 | S368 and(imaging or ccd or camera or CMOS or IR)same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:33 |
| S384 | 650 | detect$3 and micro adj defects and(semiconductors or wafer$1 or silicon oer insulator adj wafer$1 or polycrystalline adj silicon) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:37 |
| S385 | 650 | detect$3 and micro adj defects and(semiconductors or wafer$1 or silicon or insulator adj wafer$1 or polycrystalline adj silicon) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:37 |
| S386 | 313 | S385 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:37 |
| S387 | 0 | S386 and(imaging or ccd or camera or CMOS or IR)same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:38 |

| S388 | 124 | S386 and(imaging or ccd or camera or CMOS or IR)captur$4 same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:39 |
| S389 | 61 | S388 and(breakage or damaged) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:41 |
| S390 | 0 | S389 and producing same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:44 |
| S391 | 0 | S385 and producing same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:44 |
| S392 | 0 | S385 and crystallographic adj structure and wafer and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:45 |
| S393 | 44 | crystallographic adj structure and wafer and ingot | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:46 |
| S394 | 19 | S393 and(imaging or ccd or camera or CMOS or IR)captur$4 same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:46 |
| S395 | 0 | S394 and producing same wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:46 |

| S396 | 0 | S394 and producing and wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:46 |
|------|---|-----|-----|----|----|------|
| S397 | 0 | S394 and (producing or obtaining or generat$3)and wafer adj image same cell adj image | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:47 |
| S398 | 1 | S394 and(compar$3 or match$3)same wafer same(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:47 |
| S399 | 6 | S394 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:48 |
| S400 | 0 | S399 and(compar$3 or match$3)same wafer same(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:48 |
| S401 | 0 | S399 and(compar$3 or match$3)and wafer and(solar adj cell or cell) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 11:48 |
| S402 | 0 | S398 and @ad<"20040202" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2010/10/21 12:56 |
| S403 | 1734 | 136/249,262,243,252,246.CCLS. | USPAT | OR | ON | 2010/10/21 13:05 |
| S404 | 1674 | 382/145,141.CCLS. | USPAT | OR | ON | 2010/10/21 13:06 |
| S405 | 2037 | 356/72,237.1,30.CCLS. | USPAT | OR | ON | 2010/10/21 13:09 |

| S406 | 8829 | 438/381,396,933,48,57,73,74,93,94,970,584,585,586.CCLS. | USPAT | OR | ON | 2010/10/21 13:12 |
| S407 | 6253 | 365/201,63.CCLS. | USPAT | OR | ON | 2010/10/21 13:14 |
| S408 | 5009 | 429/185,162,210,90,217,218.1,337,59,157,223.CCLS. | USPAT | OR | ON | 2010/10/21 13:17 |
| S410 | 9076 | 257/461,414,428,431,461,E27.089,E27.001,E27.009,E27.01,E27.07,E27.081, E27.084,E27.085,E27.086,E27.089,E27.081,E27.098,E27.101,257,E27.122, E27.127,E27.128,E31.001,E31.11,E31.113,E31.114,E31.115.CCLS. | USPAT | OR | ON | 2010/10/21 13:27 |
| S411 | 1905 | 204/252,193,194,242,252.CCLS. | USPAT | OR | ON | 2010/10/21 13:31 |

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